

## Product Overview

X series is an integrated and highly efficient semi-automatic wafer probe platform that is specialized in testing the performance of various advanced chips. It integrates various functions such as electric light wave and microwave, etc. It has the highest temperature width and test accuracy in the industry at present, and can match various test application environments, providing reliability wafer testing within -60 ~300 wide temperature range.

## Basic Information

<b>Product number</b>	X6/X8/X12	<b>working environment</b>	Open type
<b>electricity demand</b>	220V,50~60Hz	<b>Control method</b>	Semi-Automatic
<b>Product Size</b>	1060mm*1610mm*1500mm	<b>equipment weight</b>	About 1500 kg

## Application direction

Equipment professional deal with 12 "8" 6 "wafer Si/GaN/SiC and other kinds of devices of advanced chip performance test, can be equipped with corresponding instruments and meters, for the I - V C - V light RF signal character such as 1 / f noise analysis, feature-rich devices, scalable high-power wafer test RF test automatic test, and can load temperature control system, satisfy the customer in the high and low temperature environment of all kinds of wafer device performance test requirements.

## Technical characteristics

The industry's most efficient CHUCK system, test efficiency increased by more than 40%

The industry's most efficient CHUCK test system running speed & GT;70mm/s, motion precision 1 m, while moving the translocation time index time 500ms, excellent system operating parameters have reached the highest level of the industry, ultra-high test accuracy and efficiency to meet all kinds of wafers and devices of high repeatability and stability test, compared with other probe brands in the industry, the test efficiency is effectively increased by more than 40%. -60 ~300 is the highest temperature wide area in the industry, with temperature control accuracy and stability better than 0.08, providing reliability wafer testing in high and low temperature environments. The compact structure design of four-